

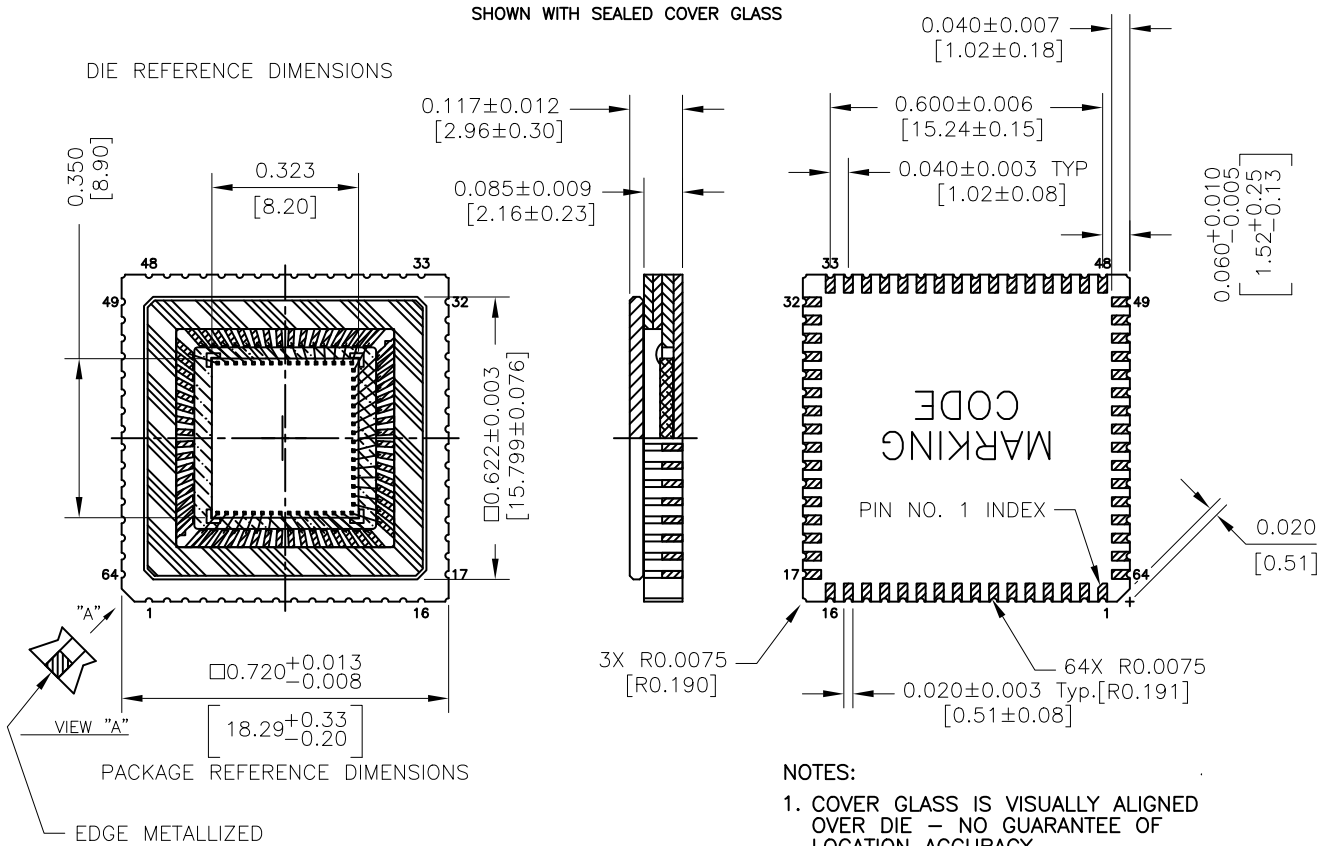
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®



CLCC64 18.29x18.29
CASE 848AF
ISSUE A

DATE 30 JUL 2014

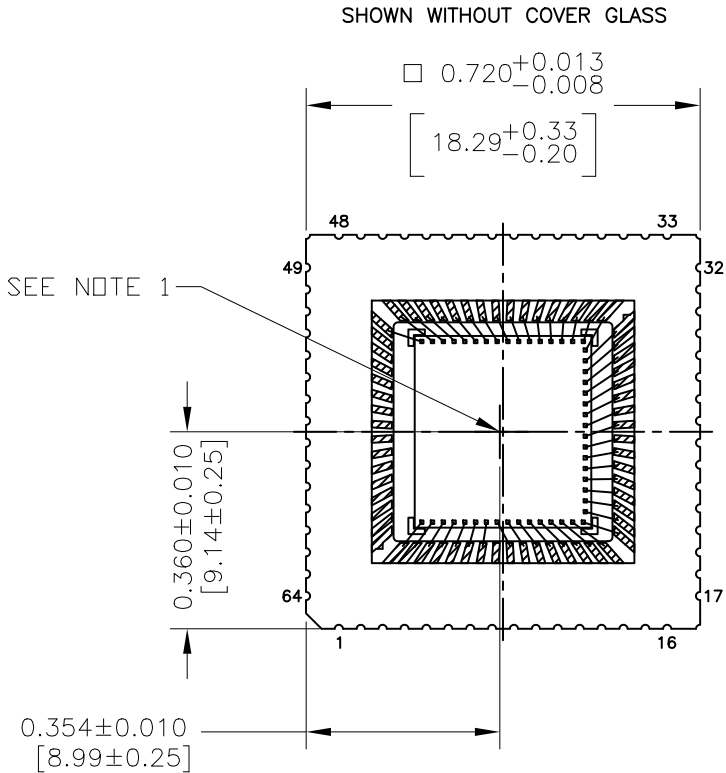


Dimensions in: Inches [mm]

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DESCRIPTION:	CLCC64 18.29X18.29	PAGE 1 OF 3

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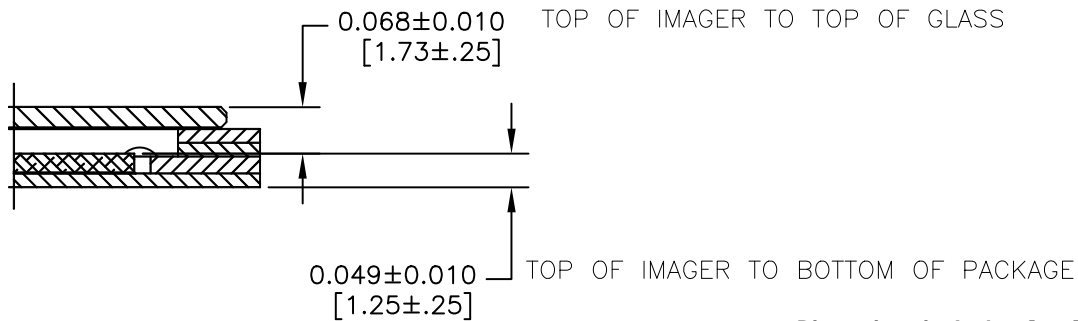
DATE 30 JUL 2014



NOTES:

1. CENTER OF IMAGE AREA IS OFFSET FROM CENTER OF PACKAGE BY $(-0.15, 0.00)$ mm NOMINAL.
2. DIE IS VISUALLY ALIGNED WITHIN $\pm 2^\circ$ OF ANY PACKAGE CAVITY EDGE.

SHOWN WITH SEALED COVER GLASS



Dimensions in: Inches [mm]

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